

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<u>In re</u> application of:)	
)	Group Art Unit: 3744
Chen et al.)	
)	Examiner: CIRIC, L.
Application No.: 10/712,708)	
)	Docket No.: JLINP174/TLC
Filed: November 12, 2003)	
)	Date: July 29, 2009
For: <u>HEAT DISSIPATION MODULE</u>)	

CERTIFICATE OF E-Filing

I hereby certify that this paper and the documents and/or fees referred to as attached herein are
being electronically filed with the United States Postal Service on **July 29, 2009**.
/Kay Harlow/

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This paper is in response to the Notice of Non-Compliant Amendment mailed on June 29, 2009, having a due date of response of July 29, 2009. A copy of the Notice of Non-Compliant Amendment is enclosed with this Response. Applicants respectfully re-submit the listing of claims, from the Amendment previously filed on February 23, 2009, which now contain the text of all pending claims, including the withdrawn claims, for the above-named application.

Amendments to the claims are reflected in the listing of claims which begin on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.